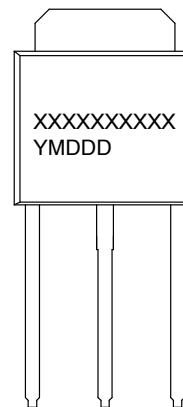
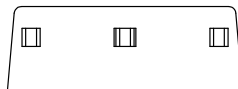
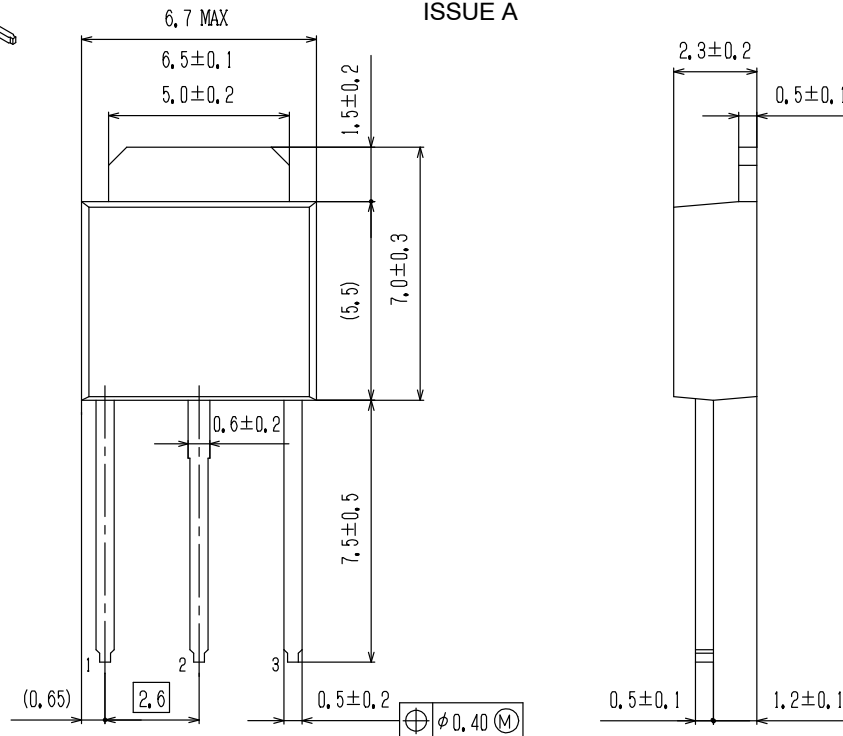


**IPAK / TP3H**  
**CASE 369AF**  
**ISSUE A**

DATE 24 OCT 2013



### GENERIC MARKING DIAGRAM\*

XXXXX = Specific Device Code

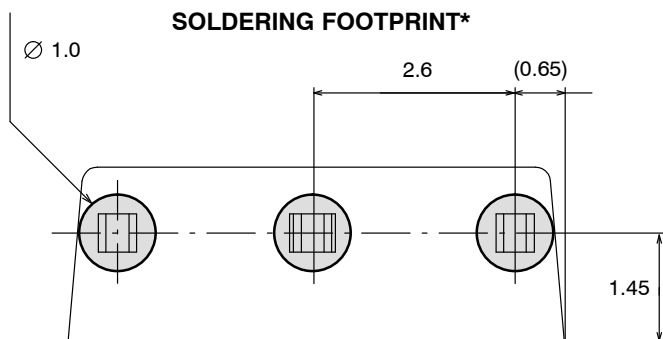
Y = Year

M = Month

DDD = Additional Traceability Data

\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "■", may or may not be present.

### SOLDERING FOOTPRINT\*



NOTE: The measurements are not to guarantee but for reference only.


(Unit: mm)

Package name
TP3H

○ Through Hole Area

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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